APPLICABLE STANDARD				
RATING	OPERATING TEMPERATURE RANGE	-35°C TO +85°C(NOTES 1)	STORAGE TEMPERATURE RANGE	-10°C TO +60°C(NOTE3)
	OPERATING HUMIDITY RANGE	20 % TO 80 % (NOTES 2)	STORAGE HUMIDITY RANGE	40 % TO 70 %(NOTE3)
	VOLTAGE	150 V AC	CURRENT	1 A

SPECIFICATIONS

ITEM	TEST METHOD	REQUIREMENTS	QT	AT
CONSTRUCTION				
GENERAL EXAMINATION	VISUALLY AND BY MEASURING INSTRUMENT.	ACCORDING TO DRAWING.	X	X
MARKING	CONFIRMED VISUALLY.		X	X
ELECTRIC CHARACTERISTICS				
CONTACT RESISTANCE	100 mA (DC OR 1000 Hz)	30 mΩ MAX.	X	—
CONTACT RESISTANCE MIILLIVOLT LEVEL METHOD.	20 mV MAX, 1 mA (DC OR 1000 Hz).			
INSULATION RESISTANCE	100 V DC.	500 MΩ MIN.	X	—
VOLTAGE PROOF	500 V AC FOR 1 min.	NO FLASHOVER OR BREAKDOWN.	X	—
MECHANICAL CHARACTERISTICS				
MECHANICAL OPERATION ⚠1	30 TIMES INSERTIONS AND EXTRACTIONS.	① CONTACT RESISTANCE: 30 mΩ MAX. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	—
VIBRATION	FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.	① NO ELECTRICAL DISCONTINUITY OF 1μs. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	—
SHOCK	490 m/s^2 DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.		X	—
ENVIRONMENTAL CHARACTERISTICS				
RAPID CHANGE OF TEMPERATURE	TEMPERATURE -55→ 5 TO 35→ +85→ 5 TO 35 °C TIME 30→ 10 TO 15→ 30→ 10 TO 15 min. UNDER 5 CYCLES.	① CONTACT RESISTANCE: 30mΩ MAX. ② INSULATION RESISTANCE: 500 MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	—
DAMP HEAT (STEADY STATE)	EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.		X	—
RESISTANCE TO SOLDERING HEAT	1) REFLOW SOLDERING ≪REFLOW AREA≫ MAX 250℃ 10 sec MAX 230℃ MIN 60 sec MAX ≪PREHEATING AREA≫ 170℃ TO 190℃ 60 sec TO 120 sec PUT THROUGH IN REFLOW FURNACE TWICE. LEAVE IN AMBIENT TEMPERATURE AND HUMIDITY FOR 1 HOUR. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE :350±5 ℃, SOLDERING TIME : 5±1 sec. NO STRENGTH ON CONTACT.	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.	X	—
SOLDERABILITY	SOLDERING TEMPERATURE : 230±5°C DURATION OF IMMERSION : SILDERING, FOR 3sec.	SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.	X	—

REMARKS
NOTE1: INCLUDE THE TEMPERATURE RISING BY CURRENT
NOTE2:NO CONDENSING
NOTE3:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFOR PCB ON BOARD.
AFTER PCB BOARD , OPERATING TEMPERATURE AND HUMIDITTY RANGE IS APPLIED FOR INTERIM STRAGE DURING TRANSPORTATION

	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
⚠1	1	DIS-H-008930	MI.SAKIMURA	TS.FUKUSHIMA	14.07.18

Unless otherwise specified, refer to IEC 60512.

APPROVED	KJ.KATAYOSE	05.01.05
CHECKED	TY.OMA	05.01.05
DESIGNED	TS.KUMAZAWA	05.01.05
DRAWN	TS.KUMAZAWA	05.01.05

Note QT:Qualification Test AT:Assurance Test X:Applicable Test

DRAWING NO. ELC4-160307-16

HRS	SPECIFICATION SHEET	PART NO.	DF14-*P-1.25H(26)	
	HIROSE ELECTRIC CO., LTD.	CODE NO.	CL538- ⚠4	1/1

FORM HD0011-2-1